

Abstract

An improved method for manufacturing circuit boards which utilizes direct printing methods to form conductor patterns from metal foils disposed on one or both sides of a conventional substrate, to form conductors directly onto a circuit board substrate, to form circuit devices directly onto a circuit board substrate, to form shields directly on circuit patterns, to form solder masks directly on circuit patterns; and to form multilayer circuit board laminates. The circuit devices formed using Applicant's direct printing processes include capacitors, resistors, inductors; and transformers.

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